

AC-LGAD TOF Status

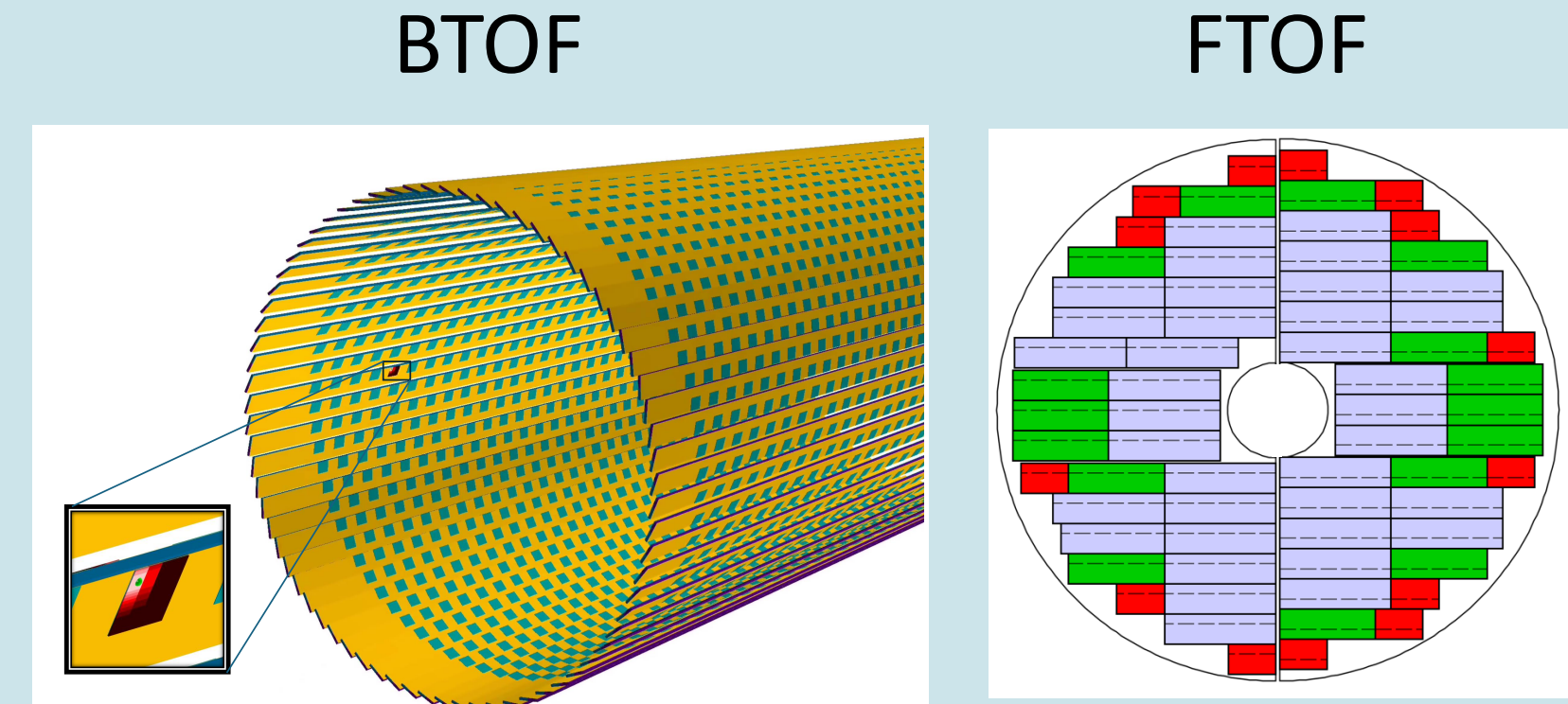
Satoshi Yano (Hiroshima University)

TIC meeting

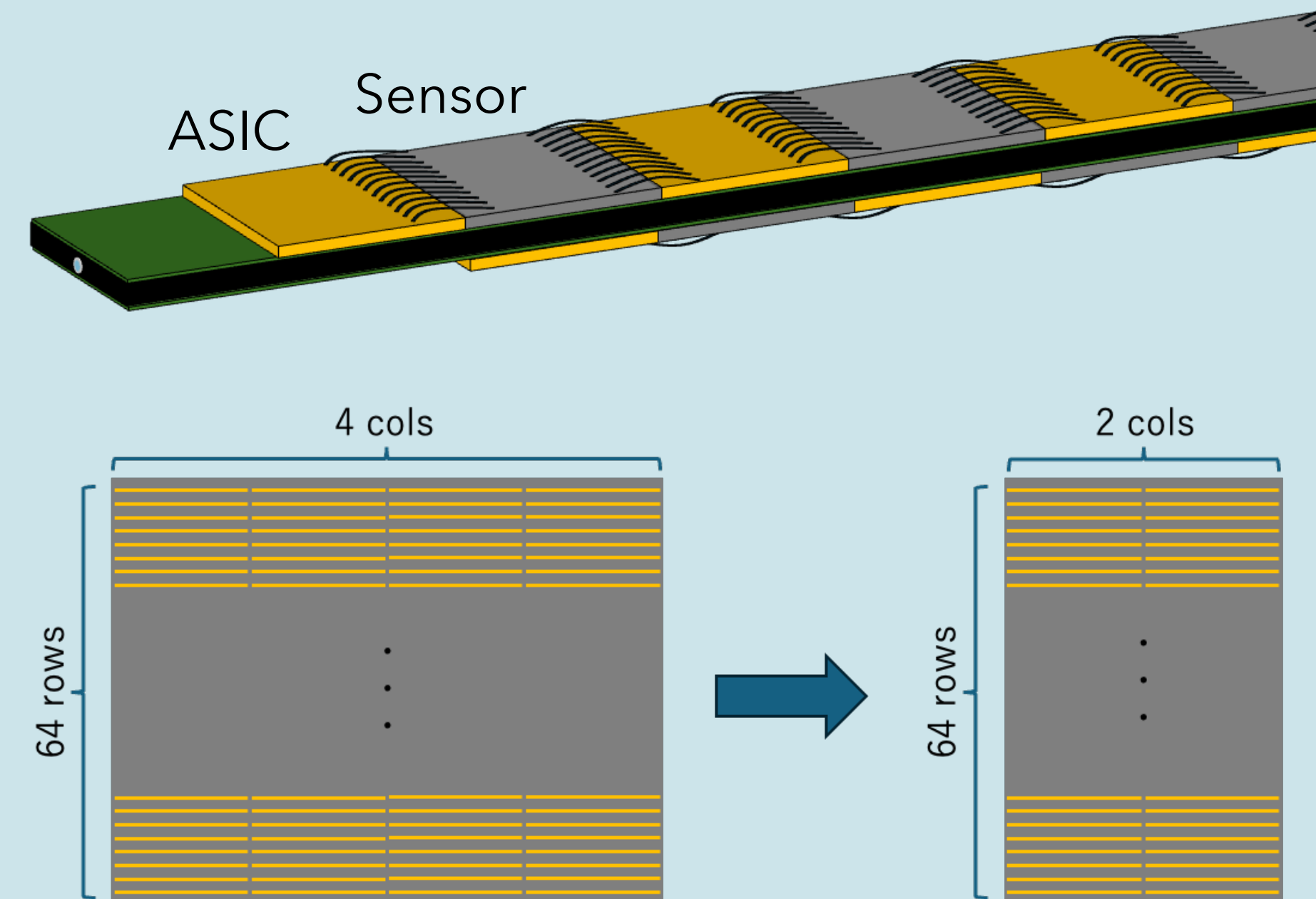
10/21/2024

Recap of recent TOF design

- AC-LGAD TOF (BTOF and FTOF) is the PID detector covering low- p region
- BTOF is composed of 144 tilted staves to form a cylindrical shape
- FTOF is composed of modules with multiple lengths of rectangle shape to make the double-face disk

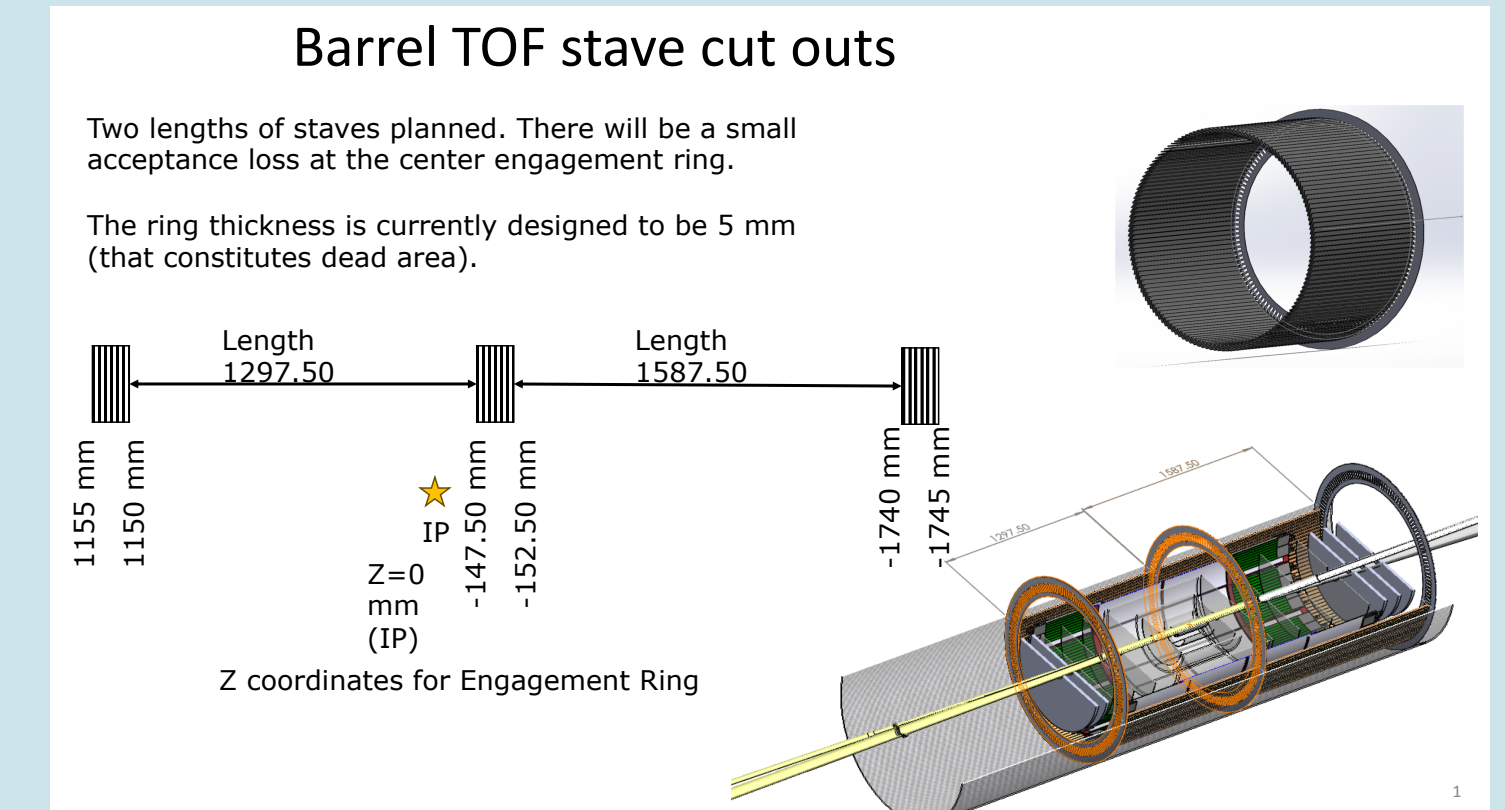


- The baseline of BTOF design has been changed
 - Stave design
 - Previous: Single side has sensors and ASICs
 - New: Double sides have sensors and ASICs
 - No acceptance gap between sensors and no direct contact between ASIC and sensor
 - Sensor
 - Previous: $3.2 \times 4 \text{ cm}^2$ with $64 \times 4 = 256$ strip-type electrodes
 - New: $3.2 \times 2 \text{ cm}^2$ with $64 \times 2 = 128$ strip-type electrodes



Issue induced by engagement ring

- An asymmetric global support structure (engagement ring) is planned to use
 - 130cm (electron-goin side) + 160cm (hadron-goin side) from the center ring
- Originally BTOF was to use the symmetric half-stave (135cm)
 - Each half-stave has 64 sensors + ASICs (32 sensors + ASICs are attached to each side)
- Designs using two staves of different lengths are now the default
 - **It is very challenging to make a 160 cm long FPC with a low material budget (a few % X/X0)**
 - Various ideas are being considered, but the material budget is likely to be large
- The asymmetric design raises the new options,
 - 1.: Each half-stave has 64 sensors + ASICs as before, but the longer side has a space at the edge of the stave (~30cm)
 - Pros: No significant design modification is necessary
 - Cons: Acceptance hole at the edge ($-1.33 < \eta < 1.54$)
 - 2.: The shorter half-stave side has 64 sensors + ASICs and the longer half-stave side has 64+ α (~15) sensors + ASICs
 - Pros: Large acceptance ($-1.33 < \eta < 1.71$)
 - **Cons: The cost increases (+13% for sensor) and some points must be redesigned especially the readout electronic.**

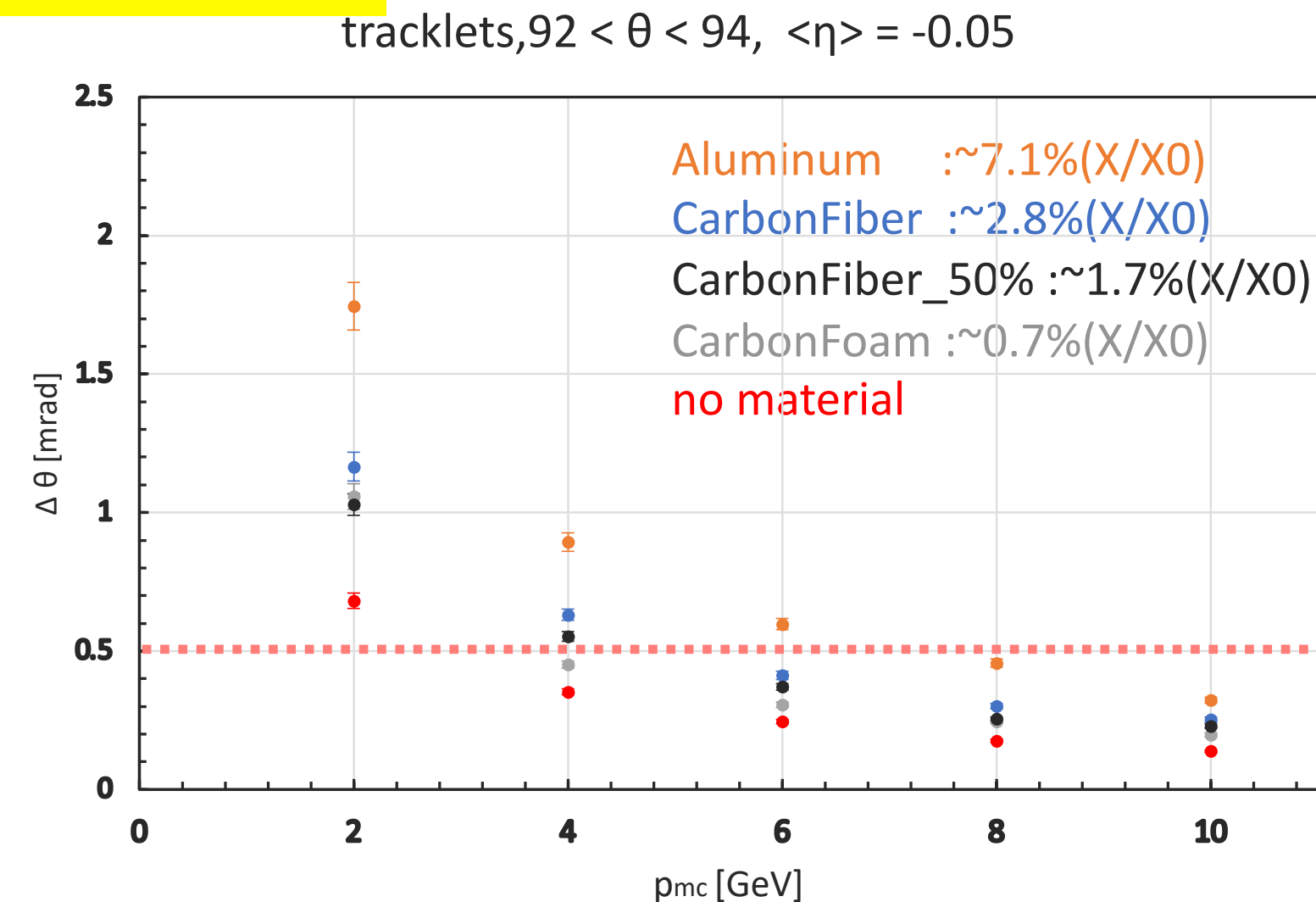
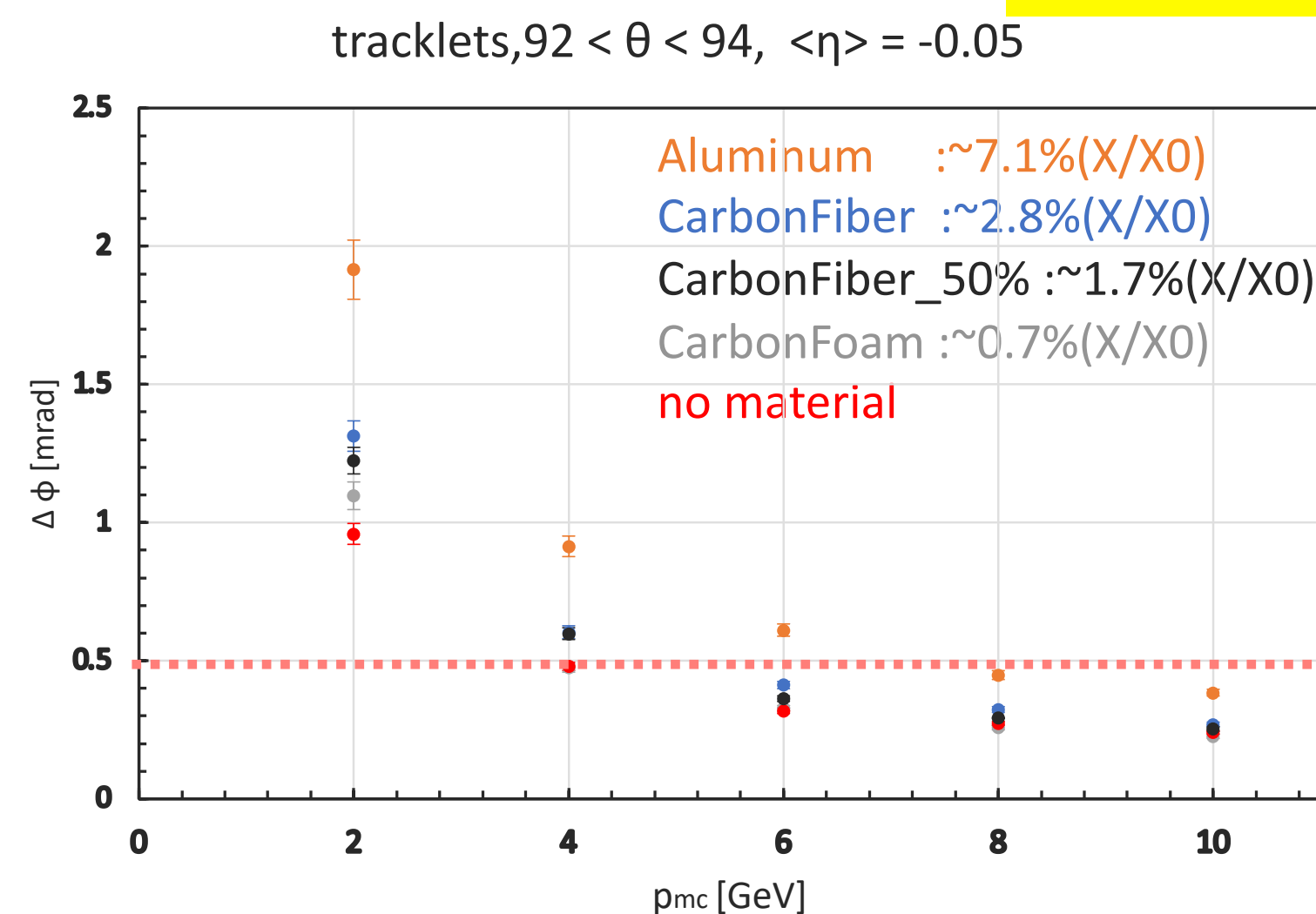


Andy's slide

Impact on angular resolution from BTOF material

- Evaluation of the effect on angular resolution on the hpDIRC surface is ongoing (by Shunichiro Muraoka, Hiroshima Univ.)
 - Single pion is injected into the full detector simulation
 - Tracklets of oMPGD and BTOF hits are used (there are still room to improve the resolution)
 - BTOF with the single-side version is used (the double-side version will be available very soon)
- The angular resolution on the hpDIRC is evaluated by varying BTOF material (**WORK-IN-PROGRESS**)
 - Several stave support structure materials are tested, no material, carbon foam, carbon fiber, or Aluminium (baseline is carbon foam)
 - The final results will be available in a month

WORK-IN-PROGRESS



- The hpDIRC requested baseline is 0.5 mrad @ 6 GeV
- Angular resolution meets the requirement even when using carbon fiber (~3% X/X0).
- The other method to estimate the track angle on the hpDIRC will be able to improve the resolution
- The information will be used to optimize BTOF design while meeting hpDIRC requirements
- **Effects on the electron identification capability by Barrel EMCal are also ongoing**

The other items

- The power supply, readout cables, and cooling pipe will be put at both sides of the stave edge

